

COMPLIANT

**HALOGEN** 

FREE

## 1.1 V to 5.5 V, Slew Rate Controlled Load Switch in TSOT23-6

#### **DESCRIPTION**

The SiP32508 and SiP32509 are a slew rate controlled load switches designed for 1.1 V to 5.5 V operation.

The switch element is of n-channel device that provides low  $R_{ON}$  of 44 m $\Omega$  typically over a wide range of input.

The devices guarantee low switch on-resistance at 1.2 V input. They feature a controlled soft-on slew rate of typical 2.5 ms that limits the inrush current for designs of heavy capacitive load and minimizes the resulting voltage droop at the power rails.

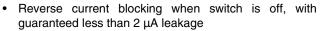
These devices feature a low voltage control logic interface (On/Off interface) that can interface with low voltage control signals without extra level shifting circuit.

SiP32508 and SiP32509 have exceptionally low shutdown current and provides reverse blocking to prevent high current flowing into the power source.

SiP32509 integrates a switch OFF output discharge circuit. Both SiP32508 and SiP32509 are available in TSOT23-6 package.

#### **FEATURES**

- 1.1 V to 5.5 V operation voltage range
- Flat low RON down to 1.2 V
- 44 m $\Omega$  typical from 1.5 V to 5 V
- Slew rate controlled turn-on: 2.5 ms at 3.6 V
- Low guiescent current < 1 µA when disabled 10.5  $\mu$ A typical at  $V_{IN} = 1.2 \text{ V}$





#### **APPLICATIONS**

- PDAs/smart phones
- Ultrabook and notebook computer
- Tablet devices
- Portable media players
- Digital camera
- GPS navigation devices
- Data storage devices
- Optical, industrial, medical, and healthcare devices
- Peripherals
- Office automation
- Networking

#### TYPICAL APPLICATION CIRCUIT

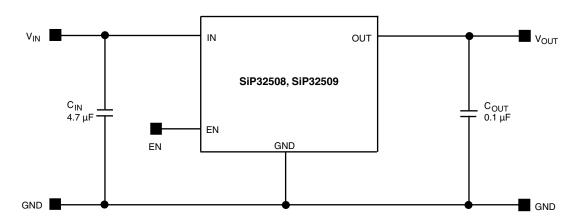


Figure 1 - SiP32508, SiP32509 Typical Application Circuit

ORDERING INFORMATION				
Temperature Range	Package	Marking	Part Number	
- 40 °C to 85 °C	TSOT23-6	LD	SiP32508DT-T1-GE3	
	130123-6	LE	SiP32509DT-T1-GE3	

GE3 denotes halogen-free and RoHS compliant

Document Number: 62754 S12-2647-Rev. A, 05-Nov-12 For technical questions, contact: powerictechsupport@vishav.com

# SiP32508, SiP32509

# Vishay Siliconix



ABSOLUTE MAXIMUM RATINGS				
Parameter	Limit	Unit		
Supply Input Voltage (V <sub>IN</sub> )	- 0.3 to 6			
Enable Input Voltage (V <sub>EN</sub> )	- 0.3 to 6	V		
Output Voltage (V <sub>OUT</sub> )	- 0.3 to 6			
Maximum Continuous Switch Current (I <sub>max.</sub> ) <sup>c</sup> 3				
Maximum Repetitive Pulsed Current (1 ms, 10 % Duty Cycle) <sup>c</sup>	6	Α		
Maximum Non-Repetitive Pulsed Current (100 μs, EN = Active) <sup>c</sup>	12			
ESD Rating (HBM)	> 8	kV		
Junction Temperature (T <sub>J</sub> )	- 40 to 150	°C		
Thermal Resistance (θ <sub>JA</sub> ) <sup>a</sup>	150	°C/W		
Power Dissipation (P <sub>D</sub> ) <sup>a,b</sup>	833	mW		

#### Notes:

- a. Device mounted with all leads and power pad soldered or welded to PC board, see PCB layout.
- b. Derate 6.66 mW/°C above  $T_A$  = 25 °C, see PCB layout.
- c.  $T_A = 25$  °C, see PCB layout

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating/conditions for extended periods may affect device reliability.

RECOMMENDED OPERATING RANGE			
Parameter	Limit	Unit	
Input Voltage Range (V <sub>IN</sub> )	1.1 to 5.5	V	
Operating Junction Temperature Range (T <sub>J</sub> )	- 40 to 125	°C	

SPECIFICATIONS							
		Test Conditions Unless Specified V <sub>IN</sub> = 5 V, T <sub>A</sub> = -40 °C to 85 °C	Limits - 40 °C to 85 °C				
Parameter	Symbol	(Typical values are at $T_A = 25$ °C)	Min.a	Typ. <sup>b</sup>	Max. <sup>a</sup>	Unit	
Operating Voltage <sup>c</sup>	V <sub>IN</sub>		1.1	-	5.5	V	
		V <sub>IN</sub> = 1.2 V, EN = active	-	10.5	17		
		V <sub>IN</sub> = 1.8 V, EN = active	-	21	30	μΑ	
Quiescent Current		V <sub>IN</sub> = 2.5 V, EN = active	-	34	50		
Quiescent Current	l Q	V <sub>IN</sub> = 3.6 V, EN = active	-	54	90		
		V <sub>IN</sub> = 4.3 V, EN = active	-	68	110		
		V <sub>IN</sub> = 5 V, EN = active	-	105	180		
Off Supply Current	I <sub>Q(off)</sub>	EN = inactive, OUT = open	-	-	1		
Off Switch Current	I <sub>DS(off)</sub>	EN = inactive, OUT = GND	-	-	1		
Reverse Blocking Current	I <sub>RB</sub>	V <sub>OUT</sub> = 5 V, V <sub>IN</sub> = 0 V, V <sub>EN</sub> = inactive	-	-	10		
		V <sub>IN</sub> = 1.2 V, I <sub>L</sub> = 100 mA, T <sub>A</sub> = 25 °C	-	47	54	mΩ	
On-Resistance	R <sub>DS(on)</sub>	V <sub>IN</sub> = 1.8 V, I <sub>L</sub> = 100 mA, T <sub>A</sub> = 25 °C	-	44	52		
		V <sub>IN</sub> = 2.5 V, I <sub>L</sub> = 100 mA, T <sub>A</sub> = 25 °C	-	44	52		
		$V_{IN} = 3.6 \text{ V}, I_L = 100 \text{ mA}, T_A = 25 \text{ °C}$	-	44	52		
		$V_{IN} = 4.3 \text{ V}, I_{L} = 100 \text{ mA}, T_{A} = 25 ^{\circ}\text{C}$	-	44	52		
		V <sub>IN</sub> = 5 V, I <sub>L</sub> = 100 mA, T <sub>A</sub> = 25 °C	-	46	52	1	
On-Resistance TempCoefficient	TC <sub>RDS</sub>		-	3570	-	ppm/°C	

SPECIFICATIONS							
		Test Conditions Unless Specified V <sub>IN</sub> = 5 V, T <sub>A</sub> = -40 °C to 85 °C	Limits - 40 °C to 85 °C				
Parameter	Symbol	(Typical values are at T <sub>A</sub> = 25 °C)	Min. <sup>a</sup>	Typ. <sup>b</sup>	Max. <sup>a</sup>	Unit	
		V <sub>IN</sub> = 1.2 V	-	-	0.3	-	
		V <sub>IN</sub> = 1.8 V	-	-	0.4 <sup>d</sup>		
EN Input Low Voltage <sup>c</sup>	V	V <sub>IN</sub> = 2.5 V -		-	0.5 <sup>d</sup>		
EN Input Low Voltage	V <sub>IL</sub>	V <sub>IN</sub> = 3.6 V	-	-	0.6 <sup>d</sup>	6 <sup>d</sup>	
		V <sub>IN</sub> = 4.3 V	-	-	0.7 <sup>d</sup>	1.7 <sup>d</sup>	
		V <sub>IN</sub> = 5 V	-	-	0.8 <sup>d</sup>	V	
		V <sub>IN</sub> = 1.2 V	0.9 <sup>d</sup>	-	-	ľ	
		V <sub>IN</sub> = 1.8 V	1.2 <sup>d</sup>	-	-		
EN Input High Voltage <sup>c</sup>	V	$V_{IN} = 3.6 \text{ V}$ 1.6 <sup>d</sup>		-	-		
	V <sub>IH</sub>			-	-		
				-	-		
		V <sub>IN</sub> = 5 V	1.8	-	-		
EN Input Leakage	I <sub>SINK</sub>	V <sub>EN</sub> = 5.5 V	- 1	-	1	μΑ	
Output Pulldown Resistance	R <sub>PD</sub>	EN = inactive, T <sub>A</sub> = 25 °C, (for SiP32509 only)	-	217	280	Ω	
Output Turn-On Delay Time	t <sub>d(on)</sub>			1.8			
Output Turn-On Rise Time	t <sub>(on)</sub>	$V_{IN} = 3.6 \text{ V}, R_{LOAD} = 10 \Omega, T_A = 25 \text{ °C}$ 1.2		2.5	3.8	ms	
Output Turn-Off Delay Time	t <sub>d(off)</sub>		-	-	0.001		

#### Notes:

- a. The algebraic convention whereby the most negative value is a minimum and the most positive a maximum.
- b. Typical values are for DESIGN AID ONLY, not guaranteed nor subject to production testing.
- c. For V<sub>IN</sub> outside this range consult typical EN threshold curve.
- d. Not tested, guarantee by design.

#### **PIN CONFIGURATION**

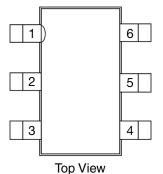


Figure 2 - TSOT23-6 Package

PIN DESCRIPTION				
Pin Number	Name	Function		
1, 2	OUT	These are output pins of the switch		
3	EN	Enable input		
4	GND	Ground connection		
5, 6	IN	These are input pins of the switch		

#### **BLOCK DIAGRAM**



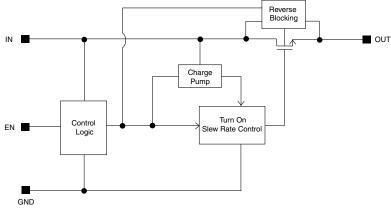


Figure 3 - Functional Block Diagram

#### TYPICAL CHARACTERISTICS (internally regulated, 25 °C, unless otherwise noted)

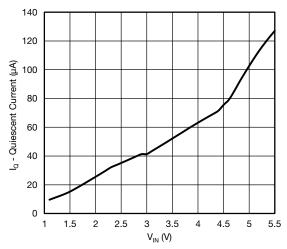


Figure 4 - Quiescent Current vs. Input Voltage

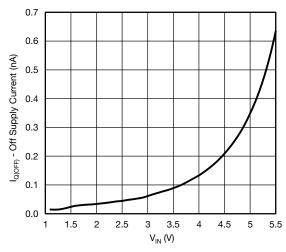


Figure 5 - Off Supply Current vs. Input Voltage

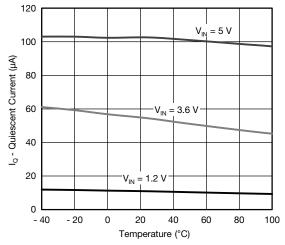


Figure 6 - Quiescent Current vs. Temperature

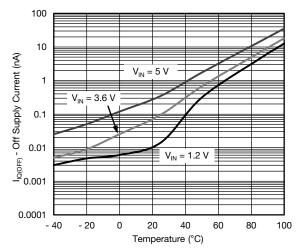


Figure 7 - Off Supply Current vs. Temperature



#### TYPICAL CHARACTERISTICS (internally regulated, 25 °C, unless otherwise noted)

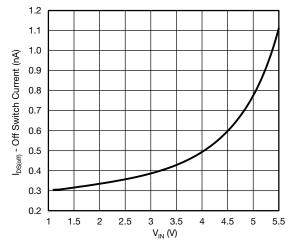


Figure 8 - Off Switch Current vs. Input Voltage

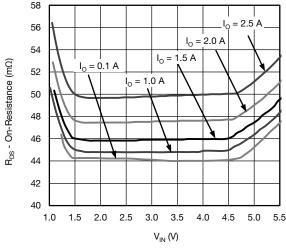


Figure 9 -  $R_{DS(on)}$  vs.  $V_{IN}$ 

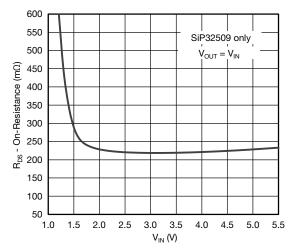


Figure 10 - Output Pull Down vs. VIN

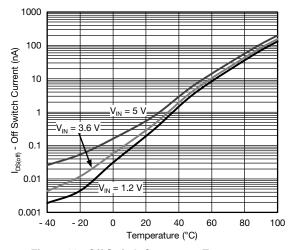


Figure 11 - Off Switch Current vs. Temperature

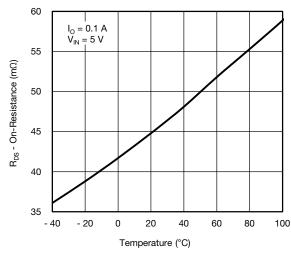


Figure 12 - R<sub>DS(on)</sub> vs. Temperature

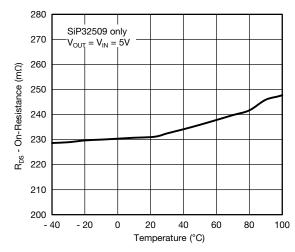


Figure 13 - Output Pull Down vs. Temperature

3.25

3.00

2.75 as Time (ms) 2.50 2.25

2.00

1.75

- 40

- 20

 $V_{IN} = 5 V$ 

 $C_{L}^{"N} = 0.1 \, \mu F$ 

= 10 Ω

#### TYPICAL CHARACTERISTICS (internally regulated, 25 °C, unless otherwise noted)

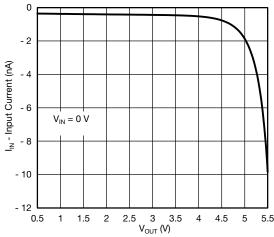
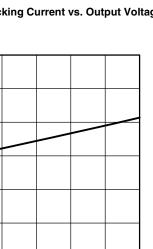


Figure 14 - Reverse Blocking Current vs. Output Voltage



Temperature (°C) Figure 15 - Rise Time vs. Temperature

40

60

80

100

20

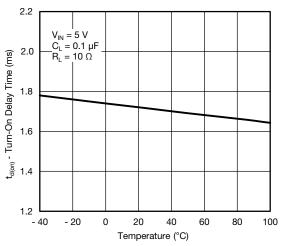


Figure 16 - Turn-On Delay Time vs. Temperature

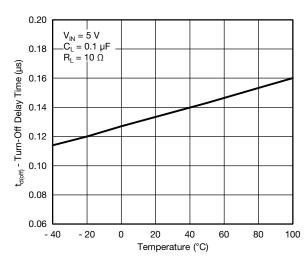


Figure 17 - Turn-Off Delay Time vs. Temperature

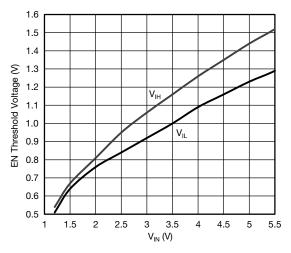


Figure 18 - EN Threshold Voltage vs. Input Voltage



#### **TYPICAL WAVEFORMS**

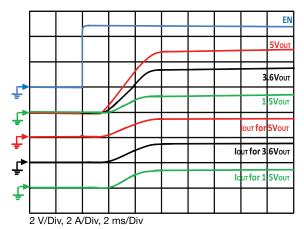


Figure 19 - Typical Turn-on Delay, Rise Time  $C_{OUT}$  = 0.1  $\mu F,\,C_{IN}$  = 4.7  $\mu F,\,I_{OUT}$  = 1.5 A

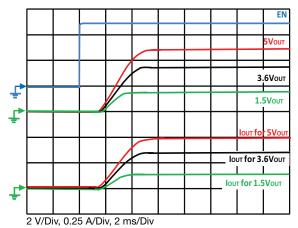
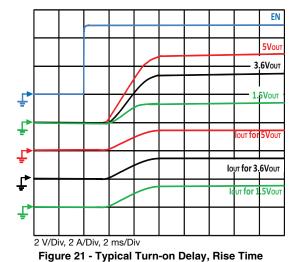


Figure 20 - Typical Turn-on Delay, Rise Time  $C_{OUT} = 0.1 \mu F$ ,  $C_{IN} = 4.7 \mu F$ ,  $R_{OUT} = 10 \Omega$ 



 $C_{OUT}$  = 200  $\mu F,\,C_{IN}$  = 4.7  $\mu F,\,I_{OUT}$  = 1.5 A

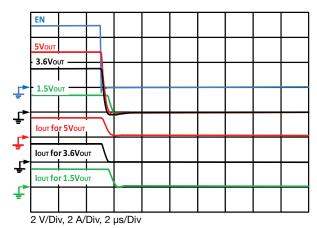


Figure 22 - Typical Fall Time  $C_{OUT}$  = 0.1  $\mu F,\,C_{IN}$  = 4.7  $\mu F,\,I_{OUT}$  = 1.5 A

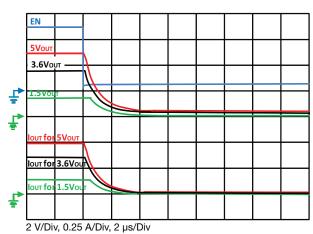


Figure 23 - Typical Fall Time  $C_{OUT}$  = 0.1  $\mu F,\,C_{IN}$  = 4.7  $\mu F,\,\,R_{OUT}$  = 10  $\Omega$ 

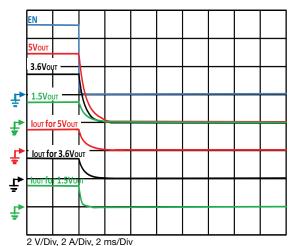


Figure 24 - Typical Fall Time  $C_{OUT}$  = 200  $\mu F,\,C_{IN}$  = 4.7  $\mu F,\,I_{OUT}$  = 1.5 A



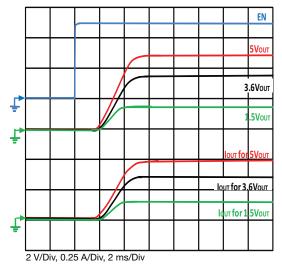


Figure 25 - Typical Turn-on Delay, Rise Time  $C_{OUT}$  = 200  $\mu$ F,  $C_{IN}$  = 4.7  $\mu$ F,  $R_{OUT}$  = 10  $\Omega$ 

#### **DETAILED DESCRIPTION**

SiP32508 and SiP32509 are advanced slew rate controlled high side load switches consisted of a n-channel power switches. When a device is enable the gate of the power switch is turned on at a controlled rate to avoid excessive in-rush current. Once fully on the gate to source voltage of the power switch is biased at a constant level. The design gives a flat on resistance throughout the operating voltages. When the device is off, the reverse blocking circuitry prevents current from flowing back to input if output is raised higher than input. The reverse blocking mechanism also works in case of no input applied.

#### APPLICATION INFORMATION

#### **Input Capacitor**

SiP32508 and SiP32509 do not require input capacitor. To limit the voltage drop on the input supply caused by transient inrush currents, a input bypass capacitor is recommended. A  $2.2 \,\mu\text{F}$  ceramic capacitor placed as close to the  $V_{\text{IN}}$  and GND should be enough. Higher values capacitor can help to further reduce the voltage drop. Ceramic capacitors are recommended for their ability to withstand input current surge from low impedance sources such as batteries in portable devices.

#### **Output Capacitor**

While these devices work without an output capacitor, an 0.1  $\mu F$  or larger capacitor across  $V_{OUT}$  and GND is recommended to accommodate load transient condition. It also helps preventing parasitic inductance from forcing VOLIT below GND when switching off. Output capacitor has minimal affect on device's turn on slew rate time. There is no requirement on capacitor type and its ESR.

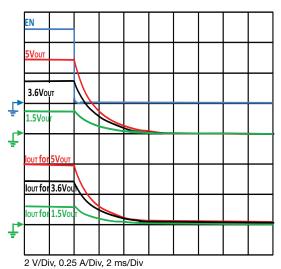


Figure 26 - Typical Fall Time  $C_{OUT} = 200 \mu F$ ,  $C_{IN} = 4.7 \mu F$ ,  $R_{OUT} = 10 \Omega$ 

#### **Enable**

The EN pin is compatible with both TTL and CMOS logic voltage levels. Enable pin voltage can be above IN once it is within the absolute maximum rating range.

#### **Protection Against Reverse Voltage Condition**

Both SiP32508 and SiP32509 contain reverse blocking circuitry to protect the current from going to the input from the output in case where the output voltage is higher than the input voltage when the main switch is off. Reverse blocking works for input voltage as low as 0 V.

#### **Thermal Considerations**

SiP32508 and SiP32509 are designed to maintain a constant output load current. Due to physical limitations of the layout and assembly of the device the maximum switch current is 3 A, as stated in the Absolute Maximum Ratings table. However, another limiting characteristic for the safe operating load current is the thermal power dissipation of the package. To obtain the highest power dissipation (and a thermal resistance of 150 °C/W) the IN and OUT pins of the device should be connected to heat sinks on the printed circuit board. Figure 21 shows a typical PCB layout. All copper traces and vias for the IN and OUT pins should be sized adequately to carry the maximum continuous current. The maximum power dissipation in any application is dependant on the maximum junction temperature,  $T_{J(max.)}$  = 125 °C, the junction-to-ambient thermal resistance for the TSOT23-6 package,  $\theta_{J-A}$  = 150 °C/W, and the ambient temperature, TA, which may be formulaically

P (max.) = 
$$\frac{T_J (max.) - T_A}{\theta_{J-A}} = \frac{125 - T_A}{150}$$



It then follows that, assuming an ambient temperature of 70 °C, the maximum power dissipation will be limited to about 367 mW.

So long as the load current is below the 3 A limit, the maximum continuous switch current becomes a function of two things: the package power dissipation and the R<sub>DS(on)</sub> at the ambient temperature.

As an example let us calculate the worst case maximum load current at  $T_A = 70$  °C. The worst case  $R_{DS(on)}$  at 25 °C occurs at an input voltage of 1.2 V and is equal to 55 m $\Omega$ . The R<sub>DS(on)</sub> at 70 °C can be extrapolated from this data using the following formula:

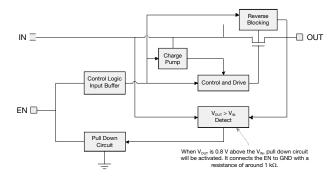
 $R_{DS(on)}$  (at 70 °C) =  $R_{DS(on)}$  (at 25 °C) x (1 +  $T_C$  x DT) Where T<sub>C</sub> is 3570 ppm/°C. Continuing with the calculation

 $R_{DS(on)}$  (at 70 °C) = 52 m $\Omega$  x (1 + 0.00357 x (70 °C - 25 °C))  $= 60 \text{ m}\Omega$ 

The maximum current limit is then determined by

$$I_{LOAD}$$
 (max.)  $<\sqrt{\frac{P \text{ (max.)}}{R_{DS(ON)}}}$ 

which in this case is 2.4 A. Under the stated input voltage condition, if the 2.4 A current limit is exceeded the internal die temperature will rise and eventually, possibly damage the device.

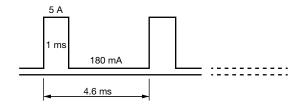


#### **Active EN Pull Down for Reverse Blocking**

When an internal circuit detects the condition of V<sub>OUT</sub> 0.8 V higher than V<sub>IN</sub>, it will turn on the pull down circuit connected to EN, forcing the switching OFF. The pull down value is about 1 k $\Omega$ .

#### **Pulse Current Capability**

The device is mounted on the evaluation board shown in the PCB layout section. It is loaded with pulses of 5 A and 1 ms for periods of 4.6 ms.



The SiP32508 and SiP32509 can safely support 5 A pulse current repetitively at 25 °C.

#### **Switch Non-Repetitive Pulsed Current**

The SiP32508 and SiP32509 can withstand inrush current of up to 12 A for 100 µs at 25 °C when heavy capacitive loads are connected and the part is already enabled.

#### **Recommended Board Layout**

For the best performance, all traces should be as short as possible to minimize the inductance and parasitic effects. The input and output capacitors should be kept as close as possible to the input and output pins respectively.

Connecting the central exposed pad to GND, using wide traces for input, output, and GND help reducing the case to ambient thermal impedance.

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## **Material Category Policy**

Vishay Intertechnology, Inc. hereby certifies that all its products that are identified as RoHS-Compliant fulfill the definitions and restrictions defined under Directive 2011/65/EU of The European Parliament and of the Council of June 8, 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment (EEE) - recast, unless otherwise specified as non-compliant.

Please note that some Vishay documentation may still make reference to RoHS Directive 2002/95/EC. We confirm that all the products identified as being compliant to Directive 2002/95/EC conform to Directive 2011/65/EU.

Vishay Intertechnology, Inc. hereby certifies that all its products that are identified as Halogen-Free follow Halogen-Free requirements as per JEDEC JS709A standards. Please note that some Vishay documentation may still make reference to the IEC 61249-2-21 definition. We confirm that all the products identified as being compliant to IEC 61249-2-21 conform to JEDEC JS709A standards.

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# AMEYA360 Components Supply Platform

## **Authorized Distribution Brand:**

























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